

- (51) International Patent Classification:
B05D 3/04 (2006.01) H01L 21/02 (2006.01)
- (21) International Application Number:
PCT/US2024/012524
- (22) International Filing Date:
23 January 2024 (23.01.2024)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
63/441,854 30 January 2023 (30.01.2023) US
- (71) Applicant: FUJIFILM ELECTRONIC MATERIALS U.S.A., INC. [US/US]; 80 Circuit Drive, N. Kingstown, Rhode Island 02852 (US).
- (72) Inventors: WOJTCZA, William A.; 4207 E. Edgewood Ave., Mesa, Arizona 85206 (US). TAKAHASHI, Kazutaka; 3627 E. Leslie Drive, Gilbert, Arizona 85296 (US).

(74) Agent: BOYLE, Craig D. et al.; Fish & Richardson P.C., P.O. Box 1022, Minneapolis, Minnesota 55440-1022 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:
— as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))

Published:
— without international search report and to be republished upon receipt of that report (Rule 48.2(g))

(54) Title: SURFACE TREATMENT COMPOSITIONS AND METHODS

(57) Abstract: This disclosure relates to methods and compositions for treating a semiconductor substrate having a pattern disposed on a surface of the substrate.